Journal of Micromechanics and Microengineering

Journal Scope
Journal of Micromechanics and Microengineering (JMM) covers all aspects of microelectromechanical structures, devices and systems, as well as micromechanics and micromechatronics. The journal aims to highlight the link between fabrication technologies and their capacity to create novel devices. Interface electronics and integration and vacuum microelectronics are also covered.

JMM focuses on:
- Fundamental work in fabrication and process technologies, including bulk and surface micromachining, LIGA, EDM, bonding, lithography, and focused ion beam techniques.
- New aspects of production techniques to create micromechanical systems and reliability aspects.
- Applications of these techniques in sensor and actuator areas. Typical devices include accelerometers, displays, resonators, micromotors, microvalves and pumps, micropositioners, microrobots, micro-optical systems and MEMS for RF applications.
- Methods to improve the achievable results, such as CAD and modelling tools to predict the performance of micromechanical systems, and metrology to evaluate their performance.

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- Microfluidic systems with on-line UV detection fabricated in photodefinable epoxy  
  \textit{R Jackman, T M Floyd, R Ghodssi, M A Schmidt and K F Jensen (MIT)}

- An experimental study of microfabricated spark gaps: wear and erosion characteristics  
  \textit{P Seriburi, D Kercher and M G Allen (Georgia Tech)}

- RF MEMS from a device perspective  \textit{J J Yao (Rockwell Science Center, CA)}

- The future of MEMS in telecommunications devices  \textit{J A Walker (Bell Labs, NJ)}

- Galvanic etching for sensor fabrication  \textit{C M A Ashruf, P J French, P M Sarro, R Kazinczi,}  
  \textit{X H Xia and J J Kelly (Delft Univ/Utrecht Univ)}

- Surface morphology of anisotropically etched single-crystal silicon  \textit{M Shikida, K Tokoro,}  
  \textit{D Uchikawa and K Sato (Nagoya Univ)}

- A novel micro-machining method for the fabrication of thick-film SU-8 embedded micro-channels  
  \textit{F E H Tay, J A van Kan, F Watt and W O Choong (National Univ of Singapore)}

- Low-temperature full wafer adhesive bonding  \textit{F Niklaus, P Enoksson, E Kälvesten and}  
  \textit{G Stemme (Royal Inst of Technology, Stockholm)}

- Simulation, dynamic testing and design of micromachined flexible joints  \textit{H Fettig, J Wylde,}  
  \textit{T Hubbard and M Kujath (Dalhousie Univ/Nortel Networks)}

- A capacitive absolute-pressure sensor with external pick-off electrodes  \textit{J-S Park and}  
  \textit{Y B Gianchandani (Univ of Wisconsin-Madison)}

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